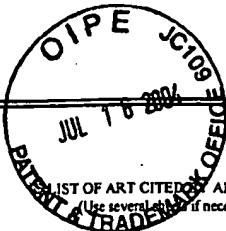


Form PTO-144 JULY 16 2004 U.S. PATENT AND TRADEMARK OFFICE LIST OF ART CITED BY APPLICANT (use several sheets if necessary)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-1684	SERIAL NO. 09/827,148		
		APPLICANT Micron Technology, Inc.					
		FILING DATE April 4, 2001		GROUP 2829			
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
<i>VN</i>	AA	4,006,909	2/8/1977	Ollendorf et al.			
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
	AI						
	AI						
	AS						
	AL						
<i>RE 350954600</i>							
<u>EXAMINER</u> <i>mark Nyguen</i>				<u>DATE CONSIDERED</u> <i>09/08/04</i>			
<small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small>							

Form PTO-1449				U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE		ATTY. DOCKET NO. MI22-16804	PRIORITY SERIAL NO. 09/137,629
LIST OF ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT David R. Hembree			
				PRIORITY FILING DATE August 21, 1998		PRIORITY GROUP 2868 2829	
U.S. PATENT DOCUMENTS							
*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
VN	AA	4,560,216	12/24/85	Egawa			
	AB	4,754,555	7/5/88	Stillman			
	AC	5,475,317	12/12/95	Smith			
	AD	5,495,667	3/5/96	Farnsworth et al.			
OTHER REFERENCES (Including Author, Title, Date, Pertinent Pages, etc.)							
	AF	5,71,595; 184; Filed 3/27/93; Drawn 2/11; Amendment filed 10/16/98; CPA filed 7/28/99; Amendment filed 3/3/00; Amendment filed 3/23/99; Original Application 6/14/92; Pending Claims <i>FD out</i>					
VN	AF	Advertisement for Probe Technology: www.idiner.com ; Interconnect Devices, Inc., 1 page; 3/6/98					
	AG	Good Things Come In Small BGA/CSP Packages: www.johnstech.com/4/handbook/page9.html ; 1 page; 3/5/98					
	AH	Product Description for Double Ended Probes, B1052 Series: www.testprobe.com/products/b1052.html ; Rika Denshi America, Inc.; 1 page; 2/4/98.					
	AI	Product Description for Test Centers, RM-500 Series Probes. www.testprobe.com/products/rm500.html ; Rika Denshi America, Inc.; 1 page; 2/4/98.					
	AJ	Product Description for Cost Effective Interconnections for High I/O Products: www.testprobe.com/products/io.htm/b1303 ; Rika Denshi America, Inc.; 1 page; 2/4/98.					
	AK	Product Description for Ball Grid Probe B1303-C3: www.testprobe.com/products/io.htm/b1303 ; Rika Denshi America, Inc.; 1 page; 2/4/98.					
	AL	Product Description for Test Socket Connectors: www.johnstech.com/4/handbook/page9.html ; 1 page; 3/5/98					
EXAMINER <i>nh Nguyen</i>				DATE CONSIDERED 09/08/04			

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

Form PTO-1449

U.S. DEPARTMENT OF COMMERCE
PATENT AND TRADEMARK OFFICEATTY. DOCKET NO.
MI22-1684SERIAL NO.
09/227,248LIST OF ART CITATIONS APPLICANT
(Use several lines if necessary)APPLICANT
Micron Technology, Inc.FILING DATE
April 4, 2001GROUP
2858 2829

U.S. PATENT DOCUMENTS

*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
VN	AA	5,503,034	4/2/1996	Amano et al.			
VN	AB	5,964,395	2/1/2000	Glovatsky et al.			
VN	AC	5,645,764	7/1997	Angelopoulos et al.			
VN	AD	5,437,189	8/1995	Brown et al.			
	AE						
	AF						
	AG						
	AH						

OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)

	A1		
	AJ		
	AK		
	AL		

EV372455567

EXAMINER

mh Nguyen

DATE CONSIDERED

09/08/04

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